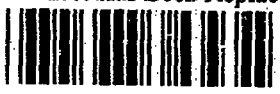
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ABSTRACT OF THE DISCLOSURE

A insulated lead frame (25) is disclosed. The lead frame has a first plurality of lead fingers (2') and a second plurality of lead fingers (27). It also has a power supply bus (28a, 28b) lying between the first plurality of lead fingers and the second plurality of lead fingers. An insulating strip (28a1, 28a2; 28b1, 28b2) lies on a face of the power supply bus near an edge of the face. Examples of a suitable dielectric strip are an adhesive type tape, such as a polyimide tape, and a nonconductive liquid, such as liquid polyimide. An insulated lead frame is useful in the manufacture of packaged semiconductor integrated circuit devices to reduce the possibility of wire bond shorting to the power supply busses. One example is a dynamic random access memory, DRAM, die having centrally disposed bonding pads (23) mounted to a lead on chip lead frame. The power supply busses of the lead on chip lead frame have dielectric strips running along their edges to reduce the possibility of shorting between the power supply busses and the crossing wire bonds (24a, 24s) that connect the lead fingers of the lead frame to the bonding pads of the DRAM.